ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: TIDA-01341</th>
<th>REV: A1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>TID #: TIDA-01341</td>
<td>GENERATED : 3.1.2017 13:14:32</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01341</th>
<th>REV: A1</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>TID #: TIDA-01341</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLT NAME = Bottom Assembly Drawing</td>
<td>GENERATED: 3.1.2017 13:14:33</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
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